# **PALLADURE 500**

For Electronic Finishing Applications

Regional Product Availability					
N. America	Japan/Korea	Asia	Europe		
<b>V</b>					

## **DESCRIPTION**

The Palladure 500 process is characterized by its ability to produce semi-bright to bright, crack-free, pure palladium deposits suitable for electronic applications.

## **ADVANTAGES**

- Exceptional contact stability
- Solution is capable of producing very high plating rates
- Low internal stress of deposit

# **DEPOSIT PROPERTIES**

Pure: 99.9+%

# **RECOMMENDED PROCESS CYCLE**

# **Connector Applications**

1. Alkaline Electroclean: Ronaclean GP-300 LF

2. Rinse

3. Acid Neutralization: 10% H<sub>2</sub>SO<sub>4</sub>

4. Rinse

5. Nickel Plate: Nikal SC

6. Nickel Activation: Ronatab Acid Activator PC-1

7. Rinse

8. Pallamet Palladium-Nickel Strike/Plate (optional)

9. Palladure 500 Plate

10. Ronovel Gold Flash

11. Rinse

12. Hot Deionized Water Rinse

13. Hot Air Dry

# **BATH MAKE-UP**

# **Chemicals Required**

Palladure 500 Make-up Solution

Palladure Palladium Salt

Palladure 500 Additive

Palladure 500 Carrier

## **MAKE-UP PROCEDURE**

- 1. Add Palladure 500 Make-up Solution to tank.
- 2. Add Palladure Palladium Salt and mix thoroughly until dissolved.
- 3. Add Palladure 500 Additive and mix thoroughly.
- 4. Add Palladure 500 Carrier and mix thoroughly.
- 5. Dilute to volume with deionized water and mix thoroughly.
- 6. Check pH and specific gravity and adjust as necessary.

Bath Make-up—Connector Applications (Metric)				
Chemicals Required	Range	Recommended		
Palladure 500 Make-up Solution	700–800 ml/l	750 ml/l		
Palladure Palladium Salt	60–65 g/l	62 g/l		
Palladure 500 Additive	8–12 ml/l	10 ml/l		
Palladure 500 Carrier	2-4 ml/l	3 ml/l		

Bath Make-up—Connector Applications (U.S.)				
Chemicals Required	Range	Recommended		
Palladure 500 Make-up Solution	70–80% v/v	75% v/v		
Palladure Palladium Salt	8–9 oz./gal.	8.3 oz./gal.		
Palladure 500 Additive	0.8-1.2% v/v	1.0% v/v		
Palladure 500 Carrier	0.2–0.4% v/v	0.3% v/v		

# **PALLADURE 500**

Operating Parameters—Metric				
Parameter	Range	Recommended		
Palladium Metal	24–26 g/l	25 g/l		
Temperature	45–55°C	50°C		
Specific Gravity	1.07–1.19	1.13		
pН	7.0–7.6	7.3		
Agitation	Moderate solution agitation combined with cathode movement  0.5–10 A/dm²  0.25 microns/minute at 1 A/dm²  0.03g per ampere minute			
Current Density				
Deposition rate				

Operating Parameters—U.S.				
Parameter	Range	Recommended		
Palladium Metal	3.2–3.5 oz./gal.	3.3 oz./gal.		
Temperature	115–130°F	I20°F		
Specific Gravity	1.07–1.19	1.13		
рН	7.0–7.6	7.3		
Agitation	Moderate solution agitation combined with cathode movement			
Current Density	5–100 A/ft²			
Deposition rate	10 microinches/minute at 10 A/ft² 0.03g per ampere minute			

## **BATH MAINTENANCE**

# Palladure 500 Make-up Solution

Palladure 500 Make-up Solution contains the basic conductivity salts.

#### Palladure Palladium Salt

To raise palladium concentration by 1.0 g/l (0.13 oz./gal.), add 2.5 g/l (0.33 oz./gal.) Palladure Palladium Salt.

# Palladure 500 Additive

Palladure 500 Additive contains the active ingredients required on solution make-up and during operation for optimum range and brightness.

# Palladure 500 Carrier

Palladure 500 Carrier is a wetting agent required on solution make-up and during operation to maintain optimum range.

# **Ammonium Hydroxide**

Ammonium hydroxide is used to raise solution pH. The quantity of ammonium hydroxide required is dependent upon operating temperature and solution pH.

# **EQUIPMENT**

Tanks: Koroseal-lined, PVDC, polypropylene or

other suitable plastics; customers should check with Rohm and Haas Electronic Materials if the suitability of any material is

in question

Anodes: Platinized titanium, platinum-clad tantalum

or platinum

Heater: Immersion quartz or titanium heaters

Filter: 1 micron filters are recommended

Pump: Sufficient capacity to turn bath over four

times per hour

# **EQUIPMENT PREPARATION**

Prior to make-up, the process tank and ancillary equipment should be thoroughly cleaned and then leached with an ammonium hydroxide solution. This procedure is particularly important for new equipment or equipment previously used for other processes.

## I. Cleaning Solution

a) Trisodium phosphate: 15 g/l (2 oz./gal.)

b) Sodium hydroxide: 15 g/l (2 oz./gal.)

# II. Neutralizing Solution

Sulfuric acid: 50 ml/l (5% v/v)

# III. Leaching Solution

Ammonium hydroxide 50 ml/l (5% v/v)

# **PALLADURE 500**

### IV. Procedure

- a) Thoroughly wash down tank and ancillary equipment with clean water.
- b) Recirculate water through the complete system to remove water soluble materials.
- c) Discard rinse water.
- d) Add cleaning solution to the tank, heat to 55–60°C (130–140°F) and recirculate through the complete system.
- e) Discard cleaning solution.
- f) Recirculate water through the complete system.
- g) Discard rinse water.
- h) Add neutralizing solution and recirculate through the complete system.
- i) Discard neutralizing solution.
- j) Recirculate water through the complete system.
- k) Discard rinse water.
- l) Add leaching solution and recirculate through the complete system.
- m) Leave leaching solution in tank for a minimum of 8 hours.
- n) Recirculate leaching solution through the complete system.
- o) Discard leaching solution.
- p) Recirculate water through the complete system.
- q) Discard rinse water.

## **PRODUCT DATA**

# Palladure 500 Make-up Solution

Appearance: Clear, colorless liquid

pH: 7.8

Specific Gravity: 1.10

# Palladure Palladium Salt

Appearance: White crystals

## Palladure 500 Additive

Appearance: Clear, colorless liquid

#### Palladure 500 Carrier

Appearance: Clear, colorless liquid

# HANDLING PRECAUTIONS

Before using this product, consult the Material Safety Data Sheet (MSDS)/Safety Data Sheet (SDS) for details on product hazards, recommended handling precautions and product storage.

**CAUTION!** Keep combustible and/or flammable products and their vapors away from heat, sparks, flames and other sources of ignition including static discharge. Processing or operating at temperatures near or above product flashpoint may pose a fire hazard. Use appropriate grounding and bonding techniques to manage static discharge hazards.

**CAUTION!** Failure to maintain proper volume level when using immersion heaters can expose tank and solution to excessive heat resulting in a possible combustion hazard, particularly when plastic tanks are used.

# **STORAGE**

Store products in tightly closed original containers at temperatures recommended on the product label.

# **DISPOSAL CONSIDERATIONS**

Dispose in accordance with all local, state (provincial) and federal regulations. Empty containers may contain hazardous residues. This material and its container must be disposed in a safe and legal manner.

It is the user's responsibility to verify that treatment and disposal procedures comply with local, state (provincial) and federal regulations. Contact your Rohm and Haas Electronic Materials Technical Representative for more information.



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